

## IN THE CLAIMS

Please amend claim 4 as marked below.

Claims 1-3. (Canceled)

Claim 4. (Currently Amended) A bump inspection method for inspecting shapes of a plurality of bumps on an inspection object each of said bumps having a planar top portion, said bumps being formed into a substantially hemispherical shape by reflowing of solder, and said top portions of all of said bumps of said inspection object being on the same plane, comprising steps of:

— a shaping step of shaping said top portions of said bumps into a planar shape by coining such that said top portions of all of said bumps of said inspection object are on the same plane;

— an illumination step of illuminating said top portions with a vertical parallel pencil of light vertical thereto through a telecentric optical system;

— an observation step of observing by a telecentric optical system having an optical axis in conformity with that of said illumination optical system;

— another observation step of observing the images of said top portions within a predetermined range of said inspection object through said observation optical system; and

— a processing step of analyzing the shapes of said bumps on the basis of the images of said top portions by said observation portion;

— said processing step including an analyzing stage of analyzing the areas of said planar top portions for said individual bumps and a judging stage of judging whether or not the areas of said top portions are within a predetermined range and judging whether heights and shapes of said bumps are within a predetermined range.

Claim 5. (Canceled)

Claim 6. (Canceled)